

Hyper-Kamiokande Outer Detector Light Injector System Technical Note

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5 Contents

6	0 Version history	3
7	1 Introduction	4
8	2 Light Injection System Overview and Requirements	4
9	3 OD PMT Saturation Studies	5
10	4 Diffuser Design	5
11	4.1 ID Diffuser Hemisphere Design	5
12	4.1.1 Inner Detector Diffuser Design	5
13	4.1.2 Diffuser Profile Measurement System	5
14	4.1.3 Diffuser Power Measurement System	7
15	4.2 OD Diffuser Design	8
16	5 OD Diffuser Mounting System and Installation	9
17	6 Pulser Board	10
18	6.1 Pulser Board Overview	10
19	6.2 Physical dimensions and construction	10
20	6.3 LED	14
21	6.3.1 Overview	14
22	6.3.2 Switching Circuit	14
23	6.3.3 Switch Selection	14
24	6.3.4 Testing	15
25	6.4 LVDS to TTL Converter	18
26	6.5 Power Supplies	19
27	6.6 Connector	20
28	6.7 Fibre Coupler	22
29	6.8 Photon Yield Tests	23
30	6.9 Production	23
31	6.10 Changes Expected from v0.9 to v1.0	23
32	6.10.1 LED and Switching Circuit	23

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33	6.10.2 LVDS-to-TTL converter	23
34	6.10.3 Power supplies	23
35	6.10.4 Connector	24
36	6.10.5 Fibre coupler	24
37	7 Server Rack and Cooling	24
38	8 LED Monitoring	25
39	9 Control System for LEDs	25
40	10 Crate Electronics	26
41	10.1 Overview	26
42	10.2 Blade	26
43	10.3 Backplane	27
44	10.4 Eurocard	28
45	11 Conclusions	29

⁴⁶ **0 Version history**

- ⁴⁷ • v0.99 - First release by Balint circulated to Liverpool group for internal review
- ⁴⁸ • v1 - [Sam]: Ported over to github for continued development, as we hit compilation
⁴⁹ time on overleaf. Initial pass through to fix wording and rewrite some sections. Also
⁵⁰ integrating Warwick TN on OD diffuser. Will add Liz's saturation studies as soon as
⁵¹ these are available. Some reordering of structure to make it flow better.

52 **1 Introduction**

53 Hyper-Kamiokande is a large scale water Cherenkov detector with two main sections, an
54 inner detector (ID) and an outer detector (OD). The OD volume of Hyper-K is a one meter
55 wide annular ring on the circumference of the detector. This space is designed to tag charged
56 particles, such as cosmic ray muons or particles from interactions in the surrounding rock,
57 entering the detector. In addition, the OD volume will be used as working space for instal-
58 lation activities. Once complete, it will be optically separated from the ID volume, and will
59 be instrumented with 3,600 outward facing 8 cm photomultipliers tubes (PMTs). These will
60 each surrounded by wavelength shifting (WLS) plates to increase photocoverage.

61 In order to achieve the precision measurements Hyper-K aims to make, precise calibration
62 of the detector is required. For the OD, a light injection (LI) system will be employed,
63 allowing for known quantities of light to be injected into the detector region. This will
64 consist of 122 diffusers and 12 collimators. The diffuser system, which is described in this
65 technical note, will be used to measure gain and timing properties of the OD PMTs, and
66 will be powered by dedicated pulsed LED sources. The 12 OD collimators are identical to
67 those uses in the ID system, and will be integrated into the ID laser system. Full details on
68 that system, along with investigations of the fibre optics that will be employed for the OD
69 system, can be found in [1].

70 **2 Light Injection System Overview and Requirements**

71 The OD diffuser system will be composed of 122 bare diffusers, installed on the outward
72 facing side of the PMT support structure. The diffuser design is discussed in Section 4.
73 These will each be illuminated by individual LED pulser boards, with 365 nm LEDs. This
74 will require at least 122 dedicated LED pulsers, and spares should be readily available for hot-
75 swapping should a board encounter issues. Full details of the pulser board design are given
76 in Section 6. The pulser boards will be powered and controlled by commercially-available
77 Field Programmable Grid Array (FPGA) boards. The control system architecture for these
78 consists of three primary components:

- 79 • **Blade:** Interfaces directly with the FPGA, distributing all differential signals into the
80 crate system.
- 81 • **Backplane:** Routes differential signals to the pulser boards and provides the primary
82 power distribution, accepting 12 V and ± 5 V inputs.
- 83 • **Eurocards:** Host the pulser boards, receive power and differential signals from the
84 backplane, and incorporate the necessary circuitry for laser triggering.

85 Further details on the control system and individual electronics crate components are given
86 in Sections 9 and 10 respectively.

87 Light will be transported between the pulsers and diffusers by a series of fibre optic
88 cables; following the investigations in [1] the Thorlabs FP400URT [2] is targeted for this.
89 Due to production limitations, it is not possible to keep all fibre path lengths the same.
90 Instead there will be five different lengths: 50 m, 80 m, 106 m, 124 m and 168 m. The
91 light output after signal attenuation and dispersion in these fibres should be as consistent
92 as possible, which will require fine tuning given the different amounts of attenuation and
93 dispersion which pulses will experience based on fibre length.

94 The initial design requirements for the system are to produce pulse widths out of the
95 diffuser of between 1–10 ns, with a photon yield in the range 1–15 million photons per pulse
96 (ppp). The 10 ns limit is driven by the timing resolution of the WLS plates. The photon

yield target here is more of a goal than a requirement, and saturation studies were performed using numbers motivated by system performance. These are summarised in Section 3.

The below paragraph should split up. The first half has been rewritten into the above paragraph, the second should be fleshed out for the photon yield test section.

Pulse width should ideally be between 1-10 ns and the photon count from 1-15 million photons, but higher limits are preferable. The lower limits are not possible to achieve, as the fibre dispersion will create a minimum pulse width, which is 4.5 ns at 180 metres, and if we try to achieve large light output it will compromise our lower light output, so we can only achieve around 100,000 photons per pulse at minimum. While these compromises are not ideal, the fibre selection limits our capabilities on hitting the required theoretical targets.

3 OD PMT Saturation Studies

4 Diffuser Design

4.1 ID Diffuser Hemisphere Design

4.1.1 Inner Detector Diffuser Design

The diffusers used to scatter input laser light in the inner detector volume are 2.54 cm half-spheres fabricated from PTFE. This is used as it

- is unaffected by immersion in water
- acts as a excellent diffuser
- is a good transmitter of UV light
- is easy to machine and clean

A mechanical drawing of the inner detector diffuser hemispheres is shown in Figure 1

4.1.2 Diffuser Profile Measurement System

A scanning system was built to measure the output characteristics of diffuser hemispheres. Enclosed in a dark box, the diffuser is mounted onto two rotary stages which gives the freedom to rotate the diffuser around the nominal axis linking the diffuser with the photosensor. This scanner only takes scans in an air medium, and the setup is illustrated in Figure 2.

A laser powered from a wall plug is used to illuminate the diffuser with light at a wavelength of 450 nm. It is triggered by a function generator with 1000 triggers per burst at a frequency of 2 kHz. The open beam is directed via a mirror, a circulator, and a lens to the fibre launch stage, and then via an optical fibre towards the diffuser. The diffuser enclosure is fixed with three screws on the double-rotation stage. Measurements of bare diffuser profiles, i.e. without enclosure, are conducted with the bare fibre end positioned in the centre of the rotation stage using a 3D printed frame. The bare fibre end is kept in place due to friction on the connection point with the diffuser hemisphere. A photograph of the rotation stage with a bare diffuser hemisphere is shown in Figure 3.

A PMT measures the diffuser spectrum at a fixed position, with 62 cm distance to the diffuser enclosure and a 3 mm pinhole aperture, restricting the solid angle viewed by the PMT to $2 \cdot 10^{-5}$ sr. For comparison, a single 50 cm PMT in the HK far detector receives light from a point source at the other side of the tank over a solid angle of approximately $2.2 \cdot 10^{-4}$ sr. The PMT signal is digitised at a sampling rate of 2500 MHz over 1000 cycles, allowing to

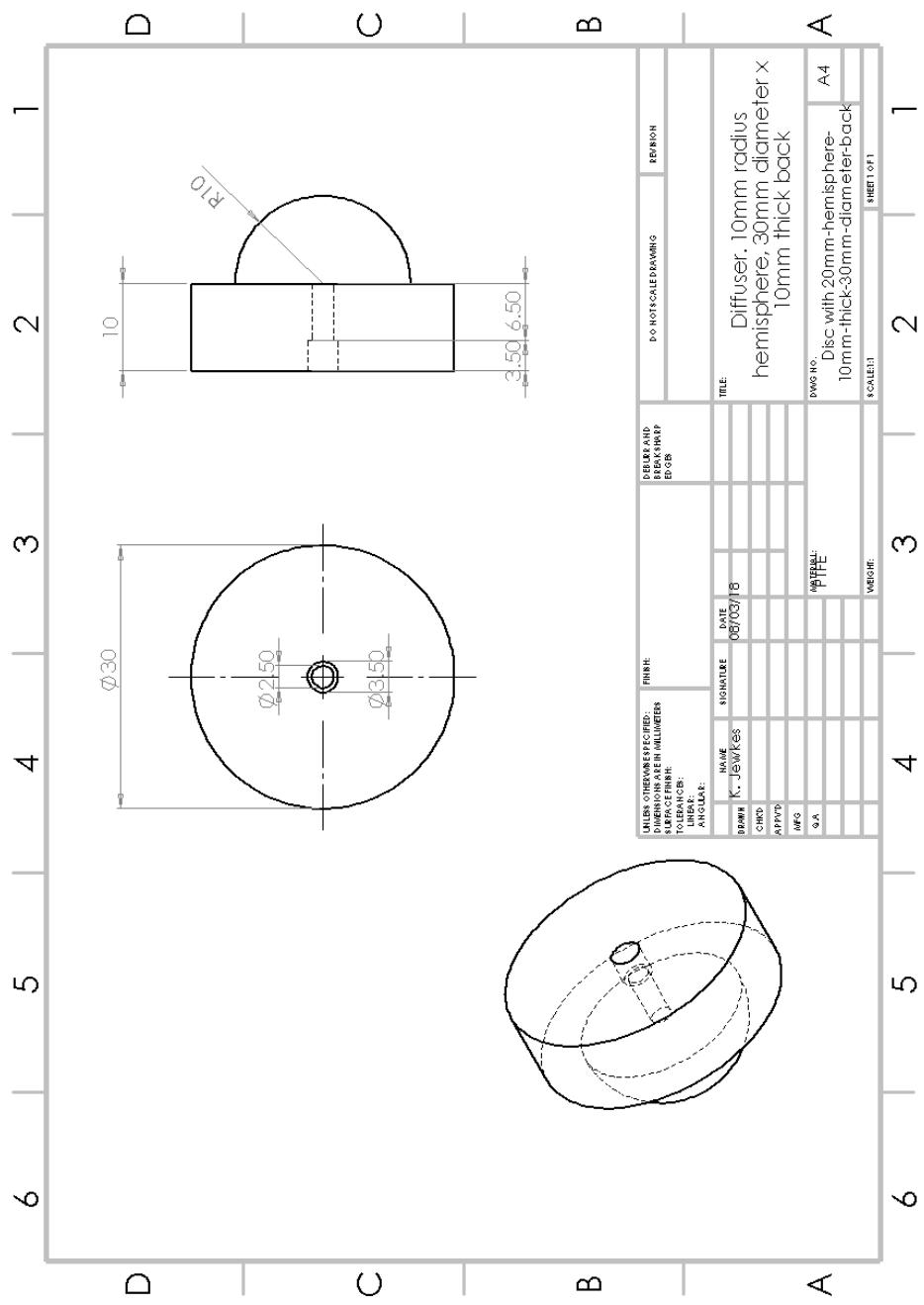


Figure 1: Bare Diffuser Mechanical Drawing

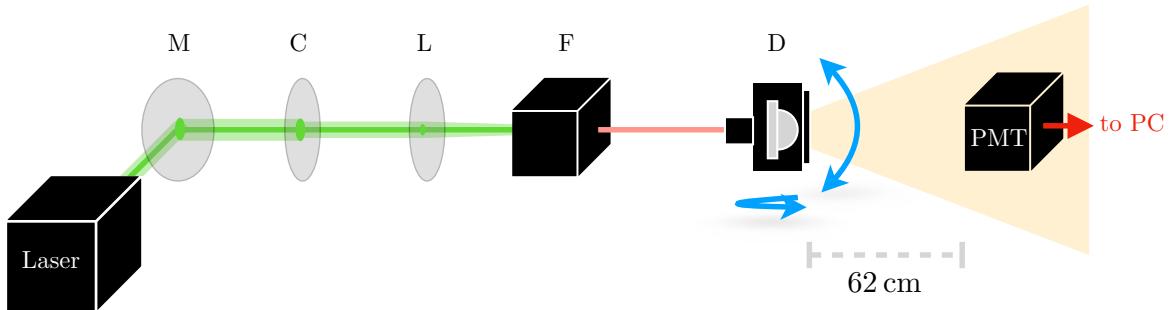


Figure 2: Setup for diffuser scans: light from the laser is directed via a mirror (M), a circulator (C), and a lens (L) to the fibre launch stage (F). From there, the light goes via an optical fibre to the diffuser (D) on the rotation stage.

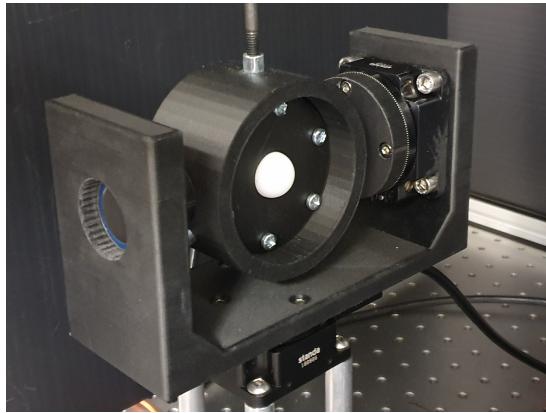


Figure 3: Rotation stage with bare diffuser hemisphere mounted using a 3D-printed frame.

137 resolve the shape of each single signal waveform. The light yield at each coordinate is then
 138 obtained as the average waveform area across all digitised signals.

139 The diffuser profile measurement system is discussed in detail in [3].

140 4.1.3 Diffuser Power Measurement System

141 In addition to the profile measurement functionality, the integrated power output from the
 142 diffuser was measured using an integrating sphere from Ophir. This sphere provides an
 143 unbiased measurement of the total light output power of any light source, regardless of the
 144 shape of the emission profile. A bespoke diffuser holder suitable for connection to one of the
 145 integrating sphere ports was 3D-printed, as was a holder for the optical fibre from the laser
 146 source.

147 A bare PTFE hemisphere was mounted into this holder and connected into the integrating
 148 sphere port. The bare end is inserted into the connection point in the same manner as for
 149 a bare profile scan. Tape was used to in order to prevent light leaking out of the back
 150 of the hemisphere during the measurement, which also helped to keep the fibre in place.
 151 The hemisphere was then illuminated with light from the same laser, this time running on
 152 a continuous rather than burst setting. On the continuous setting light is supplied in a
 153 sinusoidal manner at a frequency of 1 kHz. Power measurements were taken once per second
 154 for a period of ten seconds to account for small fluctuations in laser intensity, the mean of
 155 which served as the final power measurement for that hemisphere.

156 In order to calculate a power ratio, a measurement of power for the bare fibre also needed
 157 to be obtained. This was done in a similar manner to a power measurement for a hemisphere,

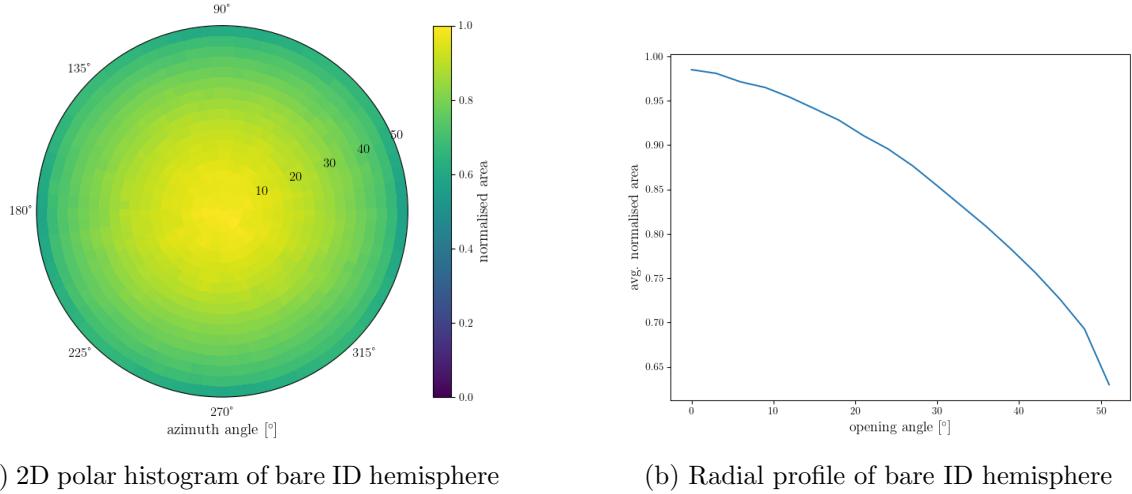


Figure 4: Profile scan of a standard bare ID diffuser hemisphere

158 using the same laser and data acquisition settings. To make the comparison between fibre and
 159 hemisphere measurement as accurate as possible, a special hemisphere was created with the
 160 fibre connection point extended into a hole that runs through the length of the hemisphere.
 161 The bare fibre can then be inserted all the way through until it pokes out of the front,
 162 allowing a power measurement for the bare fibre to be taken with the conditions inside the
 163 integrating sphere as close as possible to hemisphere measurements. The ratio of hemisphere
 164 power to fibre power can then be taken to determine the amount of light lost.

165 A table of systematics for the power ratio measurement is shown in Table I. Rotation
 166 refers to changing the orientation at which the diffuser is placed into the holder, and dif-
 167 fuser re-insertion refers to removing the diffuser from the holder and replacing it. Fibre
 168 re-insertions refers to disconnecting and re-connecting the fibre into the diffuser, while bare
 169 fibre refers to dis- and re-connecting the fibre when taking bare fibre measurements. This
 170 results in a total systematic of 5.3% for a diffuser measurement and 1.8% for a fibre mea-
 171 surement, and therefore an uncertainty of 5.6% in a power ratio measurement.

Systematic	Std. dev. (%)
Rotation	1.4
Diffuser re-insertion	1.0
Fibre re-insertion	5.0
Bare fibre re-insertion	1.8

Table I: Integrating sphere systematics for the power ratio measurement.

172 4.2 OD Diffuser Design

173 The original intention was to use the same diffuser hemisphere design for the OD diffusers
 174 as will be used for the ID diffusers. However, the standard diffuser emits less than 20% of
 175 the power delivered by an optical fibre. As there are a number of interfaces in the optical
 176 pathway between the light source and the diffuser, and as the light source for the OD will be
 177 LEDs, this was considered too low to be able to effectively illuminate the OD space. Neither
 178 the number of interfaces in the optical chain, nor the light source can be changed easily, but
 179 it is possible that an alternate design of the diffuser hemisphere could yield more light.

180 Light is lost to two mechanisms in the standard diffuser; absorption by the PTFE and



Figure 5: A prototype of the OD diffuser with a 2 mm top hat.

181 backscattering. Both loss mechanisms would be minimised if there were less PTFE in the
 182 light path. The design for the OD diffuser section was modified to be the shape of a top
 183 hat, as shown in Figure 5. The optimal depth was studied by taking profile and power
 184 ratio measurements using the same diffuser, but at smaller and smaller depths; after each
 185 measurement was completed, 2.0 mm was cut from the top-hat, and the measurements were
 186 re-taken. This procedure was repeated until the top-hat was 2.0 mm high.

Top-hat depth (mm)	Power ratio (%)
10.0	19.2
8.0	32.4
6.0	31.5
4.0	42.1
2.0	55.2

Table II: Power ratio measurements for each depth of the top-hat

187 Results of the power ratio measurements are shown in Table II. As expected, power ratio
 188 increases with decreasing top-hat depth, making the optimum depth 2.0 mm. The profile as
 189 shown in Figure 6 confirms that the shape of the profile is still suitable.

190 Based on these studies, we propose to change the OD diffuser design from a hemisphere
 191 to a top-hat with a 2.0 mm height above the base. The diffuser will still be fabricated from
 192 PTFE, but this new design (i) emits more light at higher emission angles (ii) doubles the
 193 amount of light that is emitted for a given LED power setting and (iii) is significantly easier
 194 to fabricate in bulk.

195 5 OD Diffuser Mounting System and Installation

196 The OD space will be illuminated by a total of 122 OD diffusers, 19 on each of the top and
 197 bottom caps, and 84 in the barrel. The barrel diffusers are distributed in 7 vertical layers
 198 each consisting of 12 OD diffusers. Due to the numbers and cost, the mounting system must
 199 be relatively small, easy to fabricate and easy to install. Installation will be carried out by
 200 workers on the gondola in the OD space after the Tyvek has been installed and as the fibres
 201 are being installed. The gondola worker will install the fibre in the OD diffuser, and fix the
 202 mount to the HK frame, oriented into the OD space. Since this is being done on the gondola,
 203 the mount needs to be small, easy to store, and straightforward to install.

204 Drawings for the OD diffuser prototype mount can be seen in Figure 7 and pictures of the

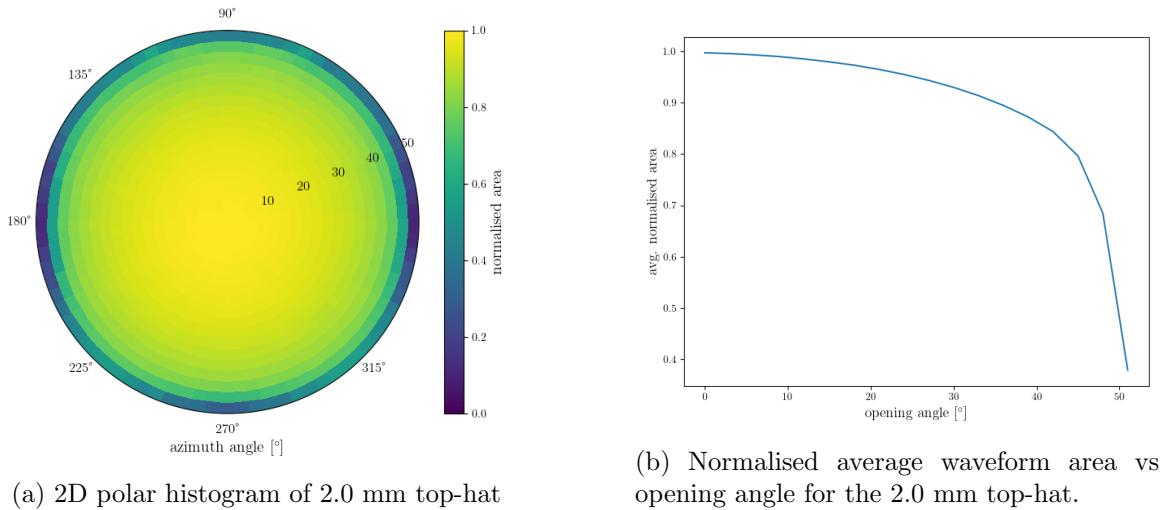


Figure 6: Profile scan of the 2.0 mm top-hat



Figure 7: (left) Front view of the prototype of the OD diffuser mount and (right) rear view of the prototype of the OD diffuser mount.

205 prototype can be seen in Figure 8. The mount is made from stainless steel and is designed
206 to hook over a horizontal frame bar, and screw in from the bottom. The PTFE mount is
207 approximately 5 cm on a side. The fibre will be installed from the back and is held in place
208 by a T-shaped component that is screwed down by the gondola worker.

209 6 Pulser Board

210 6.1 Pulser Board Overview

211 The pulser board was designed to be a more efficient and compact version compared to
212 Super-Kamiokande UK Light Injection system, improving on efficiency, functionality, and
213 light output. The pulser board is a rather simple board designed for low cost production.
214 This section explains each circuit, component selection and design decision. As of writing,
215 the board development is v0.9. v1.0 will be ready by September and will have only minor
216 changes and adjustments compared to v0.9, mostly centered on refinement and removing the
217 prototyping circuit.

218 6.2 Physical dimensions and construction

219 The dimensions of the Printed Circuit Board (PCB) were selected to be as compact as prac-
220 ticable, while still providing sufficient area for the secure mounting of a fibre coupler and for

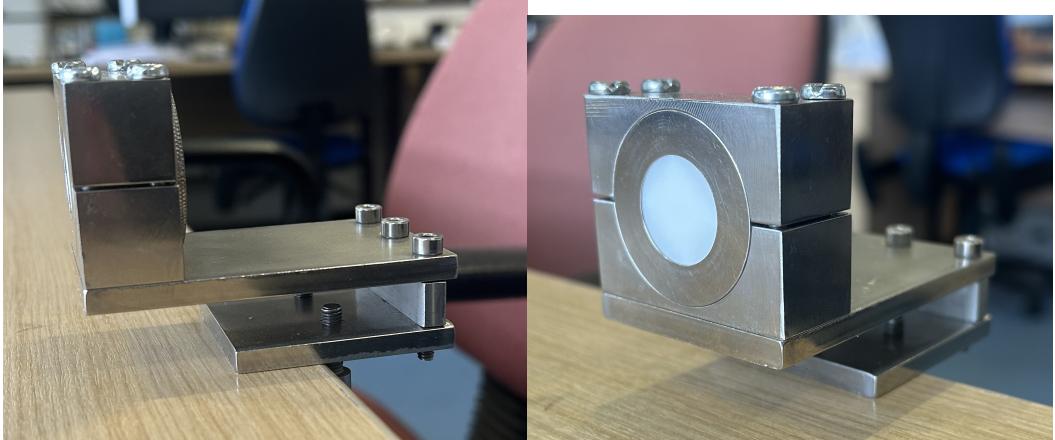


Figure 8: (left) Side view of the prototype holder and (right) front view of the prototype holder.

the components. The final board size is 50 mm × 30 mm. This configuration permits electrically noisy components, such as switching power supplies and the Low Voltage Differential Signal to Transistor Transistor Logic (LVDS-to-TTL) converter to be positioned at a maximum distance from the switching circuitry, thereby minimising potential electromagnetic interference.

Although it is technically feasible to further reduce the board size, preliminary design studies and practical build indicated no substantial benefit in doing so. The board density cannot be significantly increased inside the crate due to FPGA LVDS count and Eurocard dimension, and cost analyses revealed negligible differences associated with a smaller PCB footprint. Furthermore, the chosen dimensions provide an adequate area for the fibre coupler and the necessary mounting holes to affix the pulser board onto the Eurocard, thereby ensuring reliable optical alignment and mechanical stability. The PCB is fabricated as a four-layer FR4 [4] board with a thickness of 0.8 mm, in accordance with the standard construction offered by PCB Train/Newbury Electronics¹, see Figure 9. Refer to Figure 10 for the 3D model of the pulser board. The Top Layer and Inner Top Layer are shown in Figure 11, and the Inner Bottom Layer and Bottom Layer are likewise illustrated in Figure 12. A combined view of all PCB layers is provided in Figure 13.

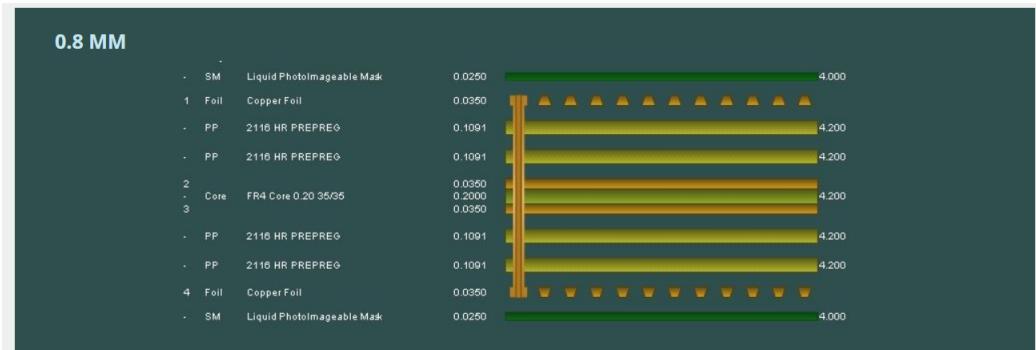


Figure 9: PCB Train's 4 Layer 0.8mm Layer Stack

¹These are trading names of the same manufacturer.

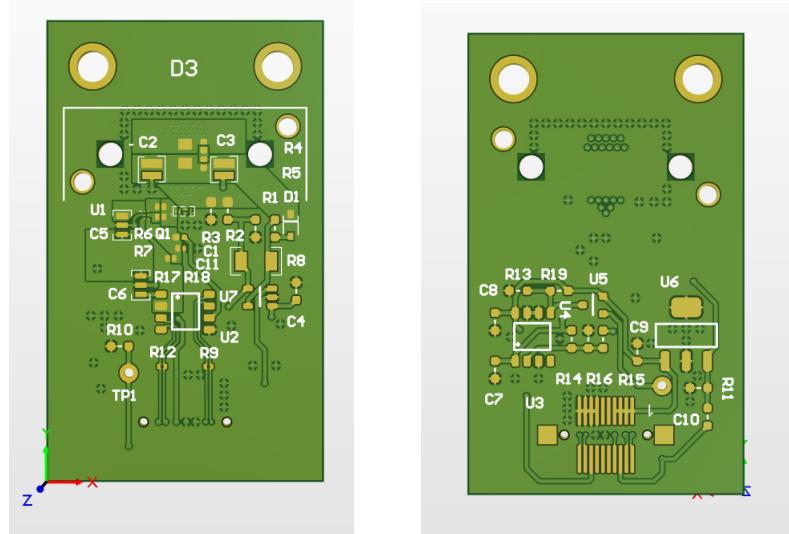


Figure 10: Pulser Board's 3D view Top and Bottom

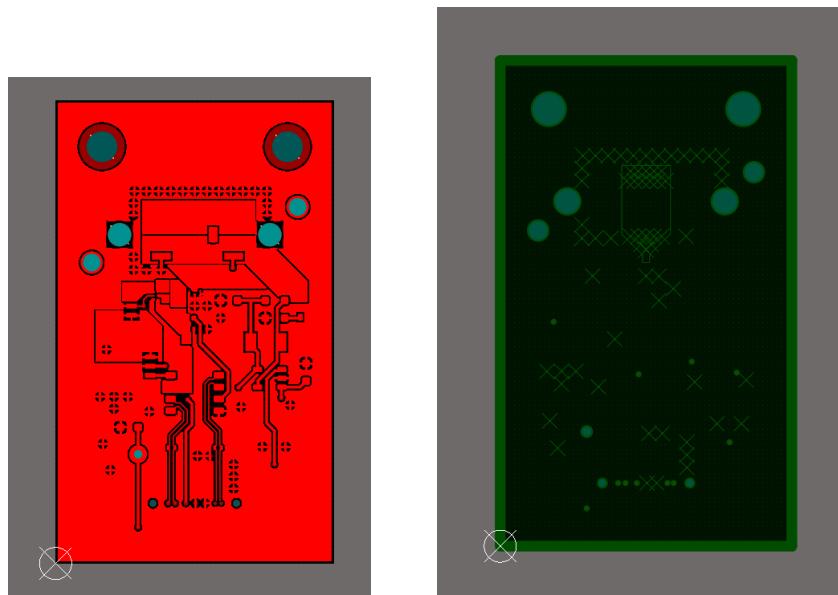


Figure 11: Pulser Board Top and Inner Top Layer

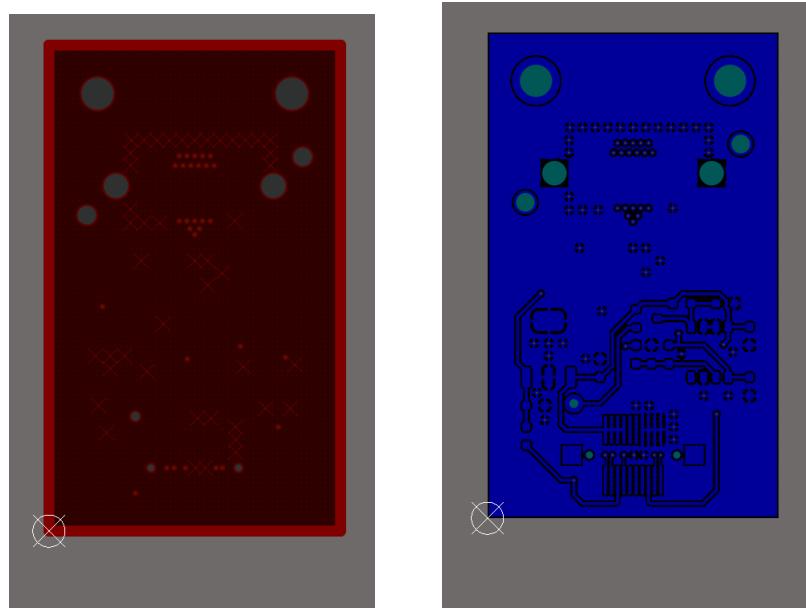


Figure 12: Pulser Board Inner Bottom and Bottom Layer

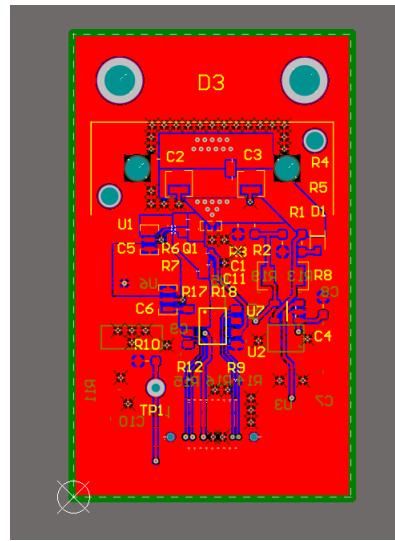


Figure 13: Pulser Board Layer Overview

238 6.3 LED

239 6.3.1 Overview

The LEDs are the most crucial component in the system as the characteristics of these primarily determine the light output, regardless of electronics. LEDs are usually not rated for such high-speed applications, which meant LEDs had to be tested and validated in-house, as datasheets do not provide the required information. The specification required was a 1–10 ns clean single pulse, sub-400 nm wavelength, small surface mount package, narrow output beam so it can be coupled to a fibre with reduced losses and a good range of photon output. Several LED packages were purchased from Kingbright and LC-LED, and their performance tested. The results of these tests are given in Section 6.3.4.

248 6.3.2 Switching Circuit

The redesign process provided a valuable opportunity to evaluate a revised layout and new components for the switching circuit. Several enhancements have since been implemented in the revised switching circuit. Most importantly, the switching side of the layout has been rerouted. In contrast to the previous configuration, where current would flow through the limiting resistor regardless of the LED state, the updated design only allows current flow when the LED is active (refer to Figure 14). This modification reduces both thermal dissipation and the overall power consumption of the system. To modulate light intensity, a variable power supply is now employed to adjust the voltage supplied to the LED. This method has proven highly effective. Tests were conducted at various voltage levels using the full 181 m length of optical fibre—the maximum expected in Hyper-K at the time of testing—and the resulting photon output ranged from approximately 1×10^5 to 2×10^7 photons per pulse. Refined testing results are shown in Section 6.3.4. Further discussion regarding the implementation and performance of the variable voltage supply is provided in Section 6.5.

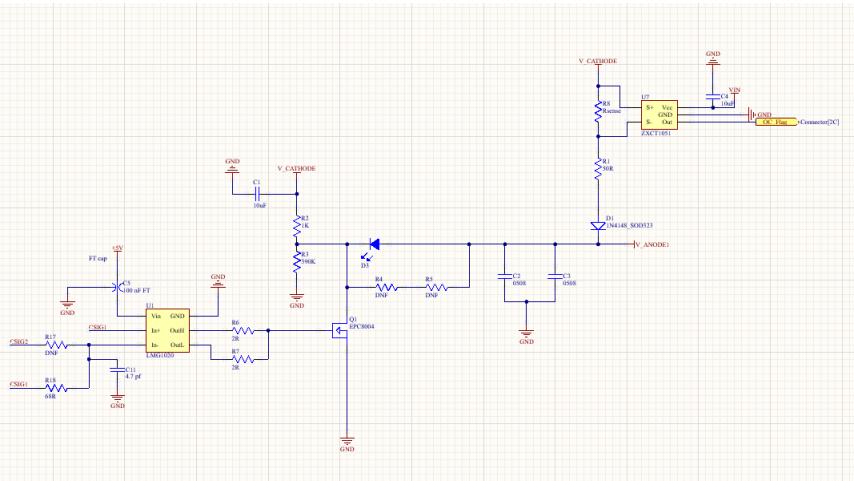


Figure 14: Switching Circuit Layout with LMG1020 and over current IC, R4 is 6.8 nH inductor and R5 is 3R3 resistor

263 6.3.3 Switch Selection

The previous iteration of the pulser board utilised a BFR92 [5] high-speed RF NPN switching transistor which was directly driven by a LVDS-to-TTL converter. In the redesign phase,

266 alternative circuit topologies were explored—particularly those suitable for generating (sub-
267)nanosecond pulses. This investigation led to the adoption of gate driver circuits. Gate
268 drivers are advantageous not only because they can power switches with challenging drive
269 requirements, but also because sub-nanosecond electrical pulses can be achieved by modu-
270 lating the enable pin with slight timing offsets.

271 The fastest commercially available gate driver identified was the Texas Instruments
272 LMG1020 [6]. This device supports pulse widths down to 1 ns, with typical rise and fall
273 times of 400 ps. Additionally, it features an enable pin that allows for precise nanosecond
274 pulse shaping ². The LMG1020 is compatible with both Gallium Nitride Field Effect Tran-
275 sistor (GaN) and Metal Oxide Semiconductor Field Effect Transistor (MOSFET) switches,
276 broadening the scope for future component integration and experimentation. It is widely
277 available and priced at £1.97 per unit in the quantities we will require for full production.

278 For the switching element, enhancement-mode GaN transistors manufactured by EPC
279 were selected due to their superior switching characteristics. This recommendation originated
280 from Nick Braam, an engineer at the University of Victoria, who contributed to the pulser
281 board design for the mPMT system. Two EPC devices were shortlisted: the EPC2012 [7] and
282 EPC8004 [8]. The EPC2012 offers a simpler footprint, which could reduce manufacturing
283 defects. However, the EPC8004 features lower parasitic capacitance, see Figure 15 for the
284 EPC2012 values and Figure 16 for EPC8004 values, leading to better high-speed performance.

285 To evaluate optical output performance, a 40 m length of FP400URT [2] optical fibre, a
286 Mouser-sourced 385 nm LED (ATS2012UV385 [9]), and a Hamamatsu H10721-210 [10] PMT
287 were used. The EPC-based configurations exhibited nearly identical pulse shapes, whereas
288 the BFR92-based circuit’s pulse shape was less sharp at identical pulse widths, as shown in
289 Figure 17. Consequently, the EPC8004 (Figure 18) was chosen for implementation. Opti-
290 mal performance of the EPC GaN switches required careful layout considerations. A layout
291 was developed in accordance with EPC’s design guidelines [11], targeting minimal parasitic
292 inductance and capacitance. The design employs two layers placed directly above one an-
293 other, utilising large copper planes and multiple vias to ensure uniform current distribution.
294 The PCB will be fabricated and assembled by PCB Train, using their 0.8 mm thick, four-
295 layer stack-up, which offers minimal inter-layer separation for optimal electrical performance
296 (Figure 9). This same layout strategy was applied to the BFR92 circuit to provide a fair
297 performance comparison.

298 A significant challenge at low pulse widths is the presence of a trailing edge or “tail” in
299 the LED output. This effect arises due to charge accumulation and the intrinsic capacitance
300 of the LED, resulting in extended decay times and pulse broadening (see Figure 19). To
301 mitigate this, a parallel modified snubber circuit was implemented, consisting of a 6.8 nH
302 inductor and a 3.3 Ω current-limiting resistor. Upon LED turn-off, the inductor generates an
303 electromotive force (EMF) that actively extracts residual charge from the LED, accelerating
304 its shutdown. The effectiveness of this approach is illustrated in Figure 20. Additionally,
305 two 0508 reverse-topology 100 nF capacitors have been incorporated. Their role is to act as
306 local energy reservoirs, providing rapid current delivery to the LED during pulse operation,
307 surpassing the response time of the main power supply.

308 6.3.4 Testing

309 For testing purposes, the previous-generation United Kingdom Light Injection (UKLI) moth-
310 erboard and associated software were utilised in conjunction with a prototype of the next-
311 generation pulser board. This prototype consisted of four distinct circuit variants: one
312 employing the EPC8004 switch, another utilising the EPC2012 switch, a third using the

²See page 12 and 13 in [6].

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Dynamic Characteristics ($T_j = 25^\circ\text{C}$ unless otherwise stated)					
C_{ISS}	$V_{\text{DS}} = 100\text{ V}, V_{\text{GS}} = 0\text{ V}$		128	145	pF
C_{OSS}			73	95	
C_{RSS}			3.3	4.4	

Figure 15: EPC2012 Capacitance Values IC

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Dynamic Characteristics[#] ($T_j = 25^\circ\text{C}$ unless otherwise stated)					
C_{ISS}	$V_{\text{GS}} = 0\text{ V}, V_{\text{DS}} = 20\text{ V}$		45	52	pF
C_{OSS}			23	34	
C_{RSS}			0.8	1.3	

Figure 16: EPC8004 Capacitance Values IC

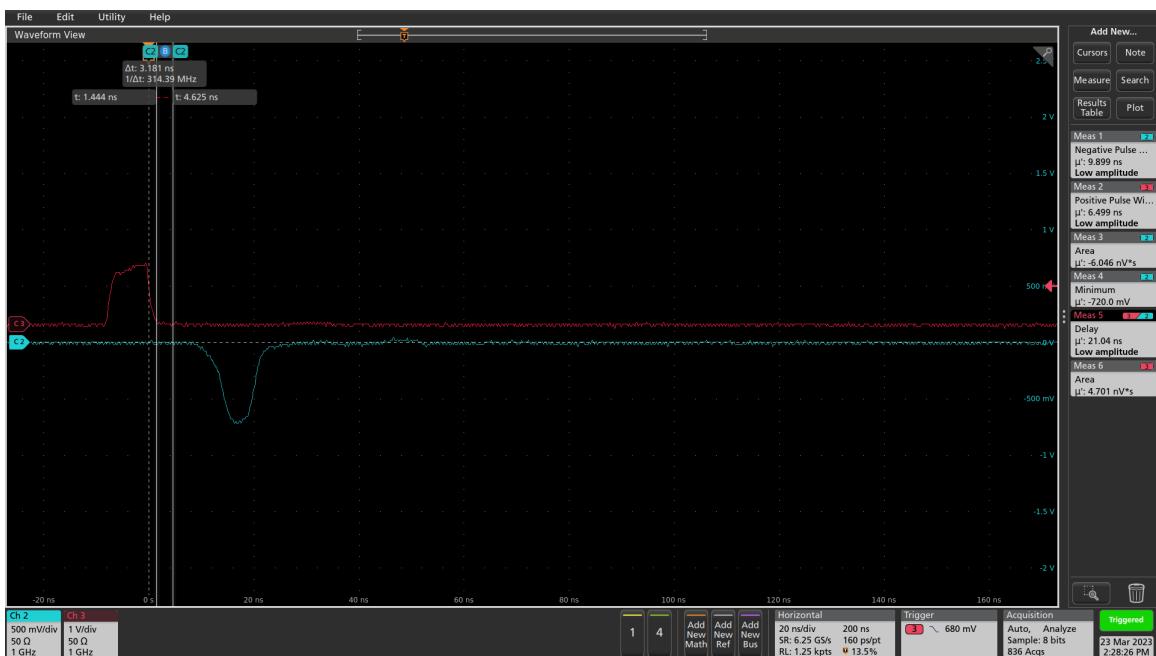


Figure 17: BFR92 Pulse Shape

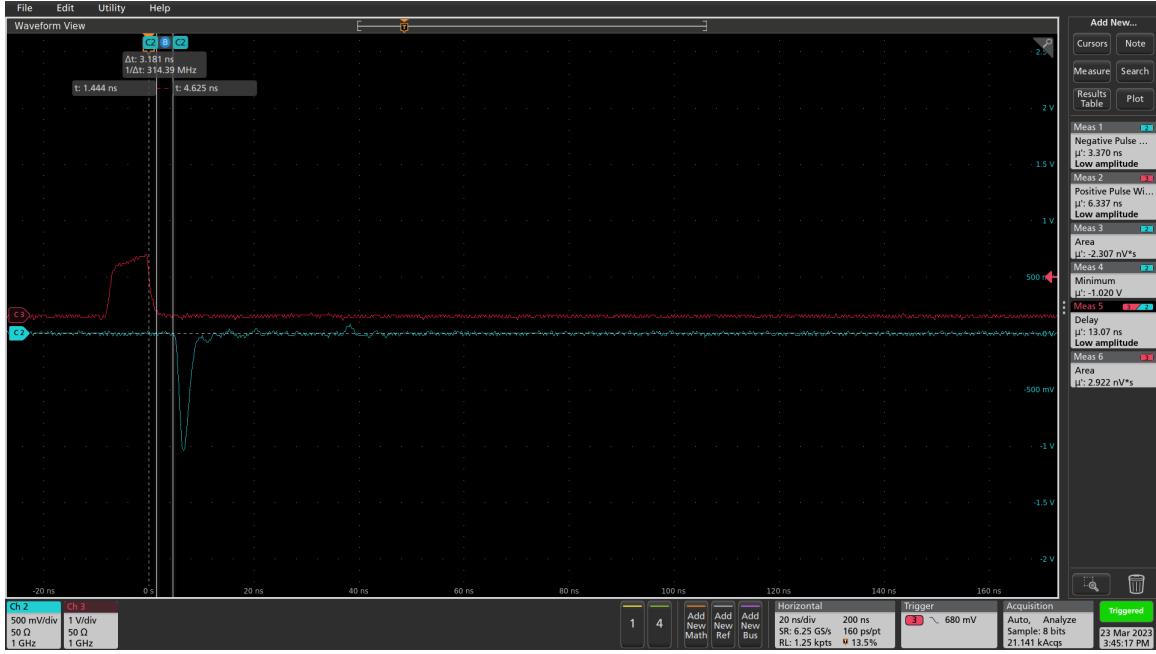


Figure 18: EPC8004 Pulse Shape

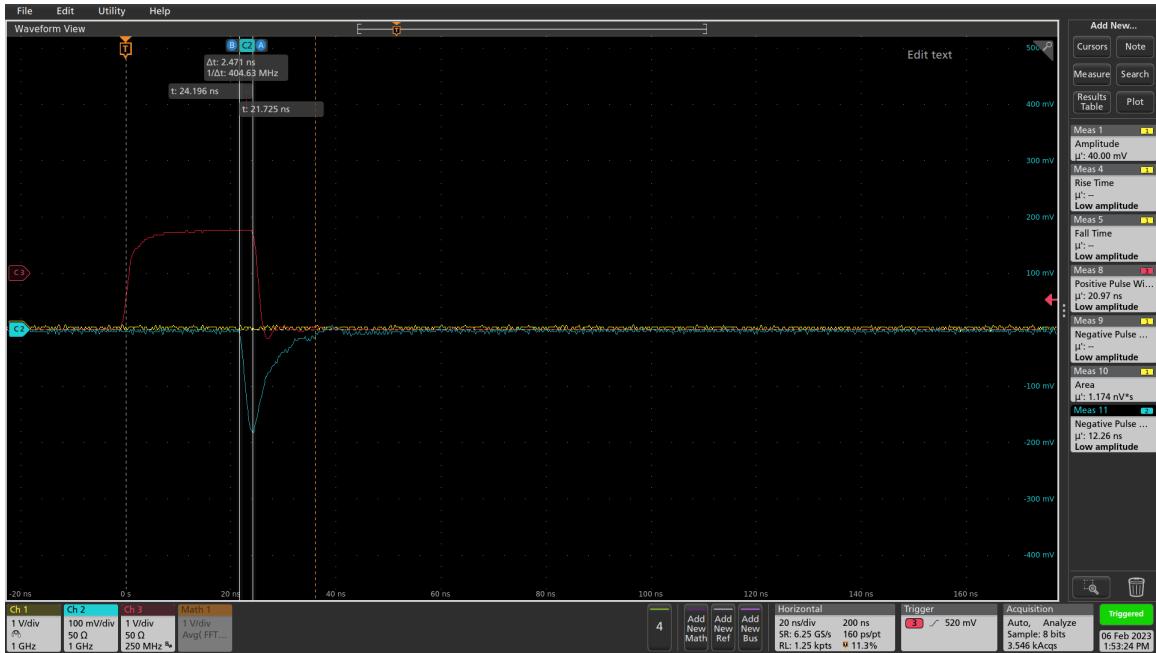


Figure 19: Pulsing Circuit With No Inductor and Resistor

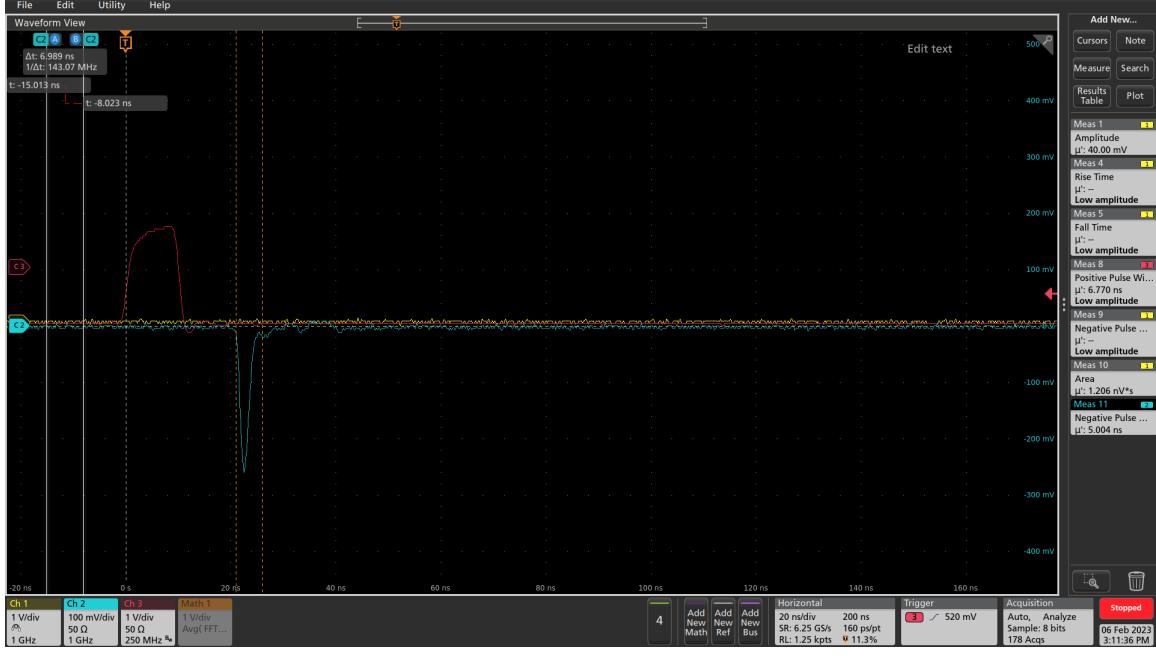


Figure 20: Pulsing Circuit With Inductor and Resistor

313 same high-speed transistor (BFR92) as implemented in the legacy system, and a fourth vari-
 314 ant incorporating an EPC2012 gate in a through-hole package instead of the standard 0805
 315 surface-mount footprint. Further evaluation was also performed using the latest pulser board
 316 prototype once they had arrived.

317 Following comparative performance evaluations, the configuration using the EPC8004
 318 switch was selected for continued use. While both the EPC8004 and EPC2012 switches ex-
 319 hibited similar electrical characteristics, the EPC8004 offered superior performance due to
 320 its lower parasitic capacitance, without any additional cost. The pulser board assembly was
 321 housed within a dark box during testing, and a 3D-printed fibre coupler was employed to
 322 facilitate light delivery. The initial focus of the evaluation was on the shape of the gener-
 323 ated optical pulse. During component selection, it was observed that the LED previously
 324 sourced from Mouser (ATS2012UV385 by Kingbright) provided acceptable performance in
 325 terms of electrical characteristics, but the optical output was suboptimal. Additionally, this
 326 LED was found to be out of stock and obsolete at the time after testing, precluding further
 327 procurement. Subsequently, four ultraviolet LEDs from LC LED were assessed—two emit-
 328 ting at 365 nm and two at 395 nm—each in both 0805 and 0603 surface-mount packages.
 329 Results demonstrated that the 0805 package LEDs provided significantly better optical cou-
 330 pling efficiency with the FP400URT optical fibre. Furthermore, the 365 nm variant exhibited
 331 superior optical power output relative to the 395 nm counterparts. Based on these findings,
 332 the LC LED UT-67UV365P [12] 365 nm LED was selected as the most suitable LED for this
 333 application.

334 6.4 LVDS to TTL Converter

335 The DS90C402 [13] from Texas Instruments was selected as the LVDS-to-TTL conversion
 336 solution. This device is a dual-channel converter, chosen primarily for its fast switching
 337 characteristics—offering both rise and fall times of approximately 500 ps. It operates at
 338 5 V and provides 5 V TTL output levels, which aligns well with the requirements of the
 339 downstream switching circuitry. The inclusion of two channels is particularly advantageous,

as it enables the generation of sub-nanosecond differential pulses by precisely offsetting the channels, as described in Switch Selection. Among commercially available devices with these specifications, the DS90C402 is the fastest and is readily available through multiple distributors.

The associated circuit was implemented in accordance with the manufacturer's recommendations provided in the datasheet. A decoupling capacitor was placed in close proximity to the power supply pin to minimise voltage ripple. Output traces were routed using polygon fills to reduce impedance and enhance signal integrity, and a continuous ground plane was placed beneath the signal layers to improve shielding and minimise electromagnetic interference. The schematic for this is given in Figure 21.

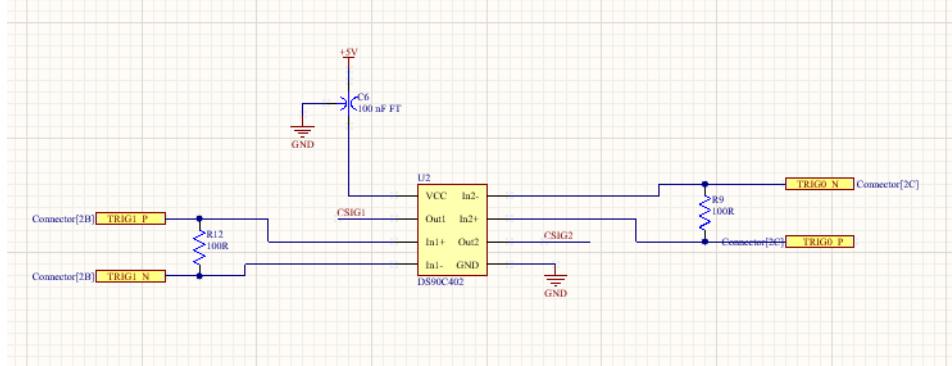


Figure 21: LVDS-TTL Converter Schematic

6.5 Power Supplies

Each pulser board is required to incorporate a variable voltage power supply dedicated to driving the LED, with an adjustable output range from 3 V to 12 V. This supply is used exclusively to modulate the LED's light output by varying the forward voltage, and consequently the current. The design specification also necessitates that the power supply be remotely controllable—i.e., capable of being switched on or off via a simple logic-level signal.

For this purpose, the LT1963A [14] adjustable low-dropout linear regulator was selected. This regulator has demonstrated reliable performance in previous pulser board iterations and offers a favourable balance of cost-effectiveness and controllability. The implementation includes standard filtering and decoupling, with layout details provided in Figure 22. The schematic provided in Figure 23 is an early version used for prototyping; the adjustable circuit has been simulated and will be tested shortly, and the enable circuit has been tested, modified and simplified. Updated schematics will be provided with v1.0 circuit.

In addition to the variable LED supply, each board requires a stable 5 V supply to power both the DS90C402 LVDS-to-TTL converter and the LMG1020 gate driver. Unlike the LED supply, this rail remains continuously powered. The 5 V supply is provided by an LM2937-5 [15], a fixed-output linear voltage regulator, which has been successfully employed in various high-speed and low-noise applications within the laboratory. The associated circuit schematic and layout and schematic are shown in Figures 24 and 25 respectively.

To meet system-level design constraints, each pulser board is equipped with its own independent 12 V input supply, ensuring that LED output intensity can be individually controlled on a per-board basis. However, the 5 V supply is common across all boards and derived locally on each pulser module. This approach allows for localised filtering and minimal power distribution path lengths, reducing the risk of noise coupling and voltage

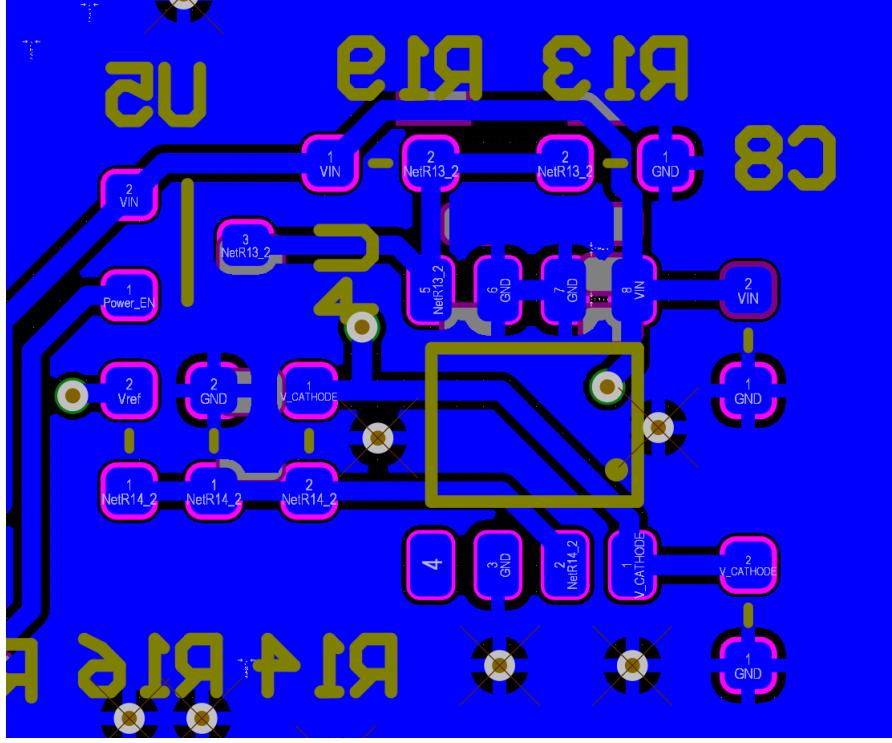


Figure 22: LT1963 Layout

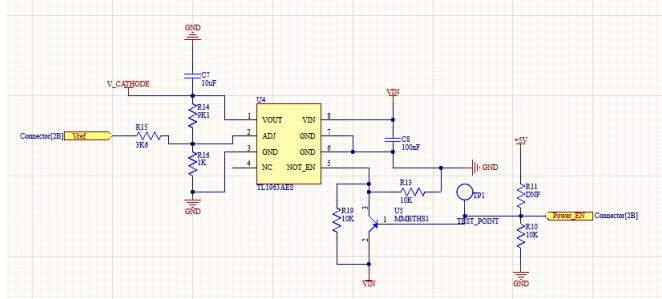


Figure 23: 12V Circuit Schematics

drop considerations that are particularly critical in high-speed circuit applications.

Power is supplied to each board via the Eurocard backplane. The 12 V input from the Eurocard simultaneously feeds both the variable (LED) and fixed (logic) power regulators on the pulser board. The LED enable function is controlled via a 5 V logic signal originating from the Eurocard’s GPIO interface. Additionally, a DAC output from the Eurocard provides a voltage control signal to the adjustment pin of the LT1963A regulator on each pulser board, thereby allowing precise, programmable control of light intensity.

6.6 Connector

The previous board connector was deemed too bulky and expensive for the larger number of channels needed in this system, leading to the process of finding a more suitable alternative. Following an evaluation of commercially available options, the Phoenix Contact female connector 1331962 [16] was selected. This connector offers several advantageous specifications: it is rated for 500 V, features a low contact resistance of $40\text{ m}\Omega$, supports a maximum current of 0.5 A, and is capable of signal transmission up to 20 Gbit s^{-1} . In addition, it is

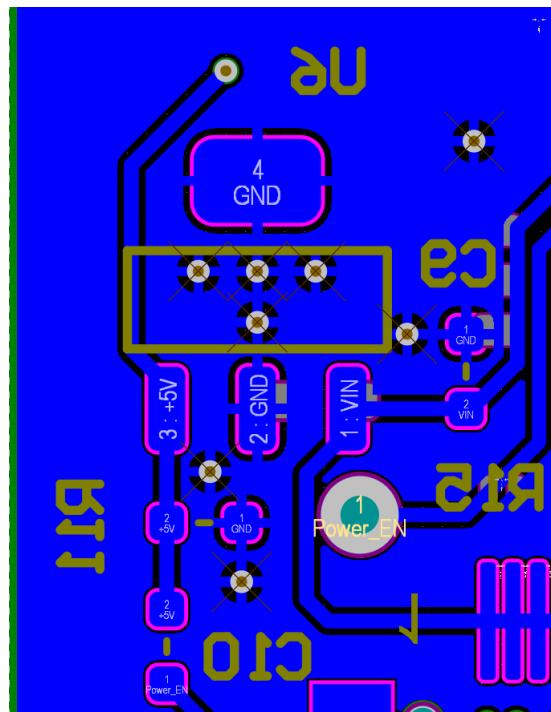


Figure 24: LM2937-5 Layout

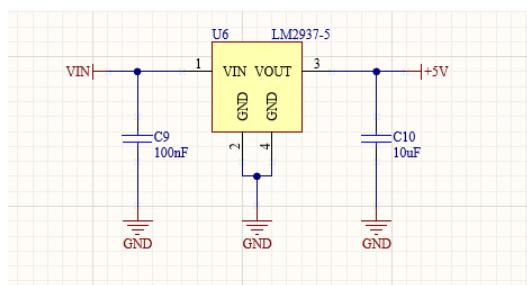


Figure 25: 5V circuit schematics

389 cost-effective, priced at approximately £0.50 per unit, with wide availability ensuring ease
 390 of procurement. Multiple height variants are available within the same series, facilitating
 391 flexible mechanical integration within the Eurocard crate system. The compact footprint of
 392 the connector allows for a reduced PCB form factor. Electrically, the high-frequency perfor-
 393 mance supports reliable LVDS signal transmission. Additionally, the compact footprint of
 394 the connector is well-suited to space-constrained PCB layouts.

395 An illustration showing the connector and corresponding circuit layout is provided in
 396 Figure 26.

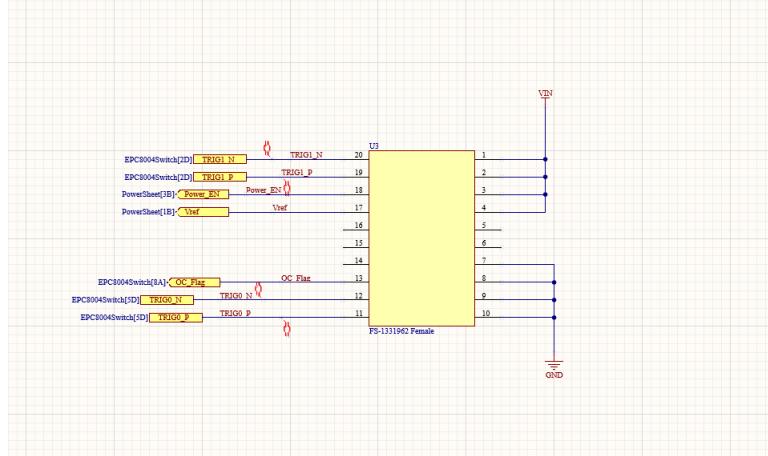


Figure 26: Connector Schematics

397 6.7 Fibre Coupler

398 During the prototyping phase, improvements were made to the PCB layout to better ac-
 399 commodate a fibre coupler. As a result, the current design includes provisions for precise
 400 mechanical mounting and alignment. Specifically, two mounting holes for M2 screws have
 401 been incorporated, enabling the 3D-printed coupler to be firmly secured to the board (see
 402 Figure 27). In addition, two dowel holes have been added to guide the coupler into posi-
 403 tion, ensuring accurate alignment over the LED. Given the tolerances associated with PCB
 404 fabrication and 3D printing, an alignment accuracy of approximately 100 µm is expected.

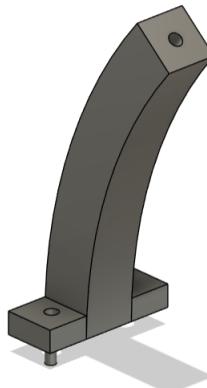


Figure 27: Old Fibre Coupler Design

405 To optimise the electrical path, capacitors have been repositioned as close as possible to

406 the LEDs. This minimises parasitic inductance and resistance, while enabling a centralised
407 layout of larger components. The resulting configuration creates a compact chamber housing
408 both the LEDs and associated capacitors.

409 An earlier design for the fibre coupler, which assumed uniform fibre lengths for all chan-
410 nels, has since been abandoned. The current approach for the LED light injection system
411 adopts five different fibre lengths, necessitating individual light attenuation for each channel.
412 This attenuation will be implemented within the coupler itself, allowing the LED output to
413 remain within the electronically controlled dynamic range.

414 The proposed design is modular, consisting of three components: a base section mounted
415 to the pulser PCB, a top section into which the fibres will be epoxied, and an intermediate
416 attenuator element. The latter will serve to space the fibre from the LED and thereby adjust
417 the optical coupling efficiency to achieve the required attenuation. While an initial prototype
418 will be developed in the near term for functional testing, the full design and validation of the
419 fibre coupler will be undertaken later, once the required fibre lengths are fixed and unlikely
420 to change. Should the project timeline require faster iteration, this can be pursued.

421 The fibre coupler will be fabricated via stereolithography (SLA) using a black resin to
422 minimise light transmission through the material. Additional light-tight testing will be
423 conducted, and black paint may be applied if further sealing is required. Furthermore, laser-
424 cut rubber gaskets will be introduced at interface points to ensure optimal optical isolation
425 and mechanical sealing.

426 **6.8 Photon Yield Tests**

427 **tests on maximising photon yield and available dynamic range should be fully described here**

428 **6.9 Production**

429 Production will be carried out using PCB Train as they are local and competitively priced,
430 and known to produce boards of good quality. Estimated cost is £12.27 per board, which
431 equates to £1,496.94 for 122 units or £1,840.5 for 150 units, and production is £4073.48 for
432 122 units for 15 days lead time, or £3985 for 150 units at 25 days lead time. The full cost
433 breakdown is shown in Figure 28

434 **6.10 Changes Expected from v0.9 to v1.0**

435 **6.10.1 LED and Switching Circuit**

436 There will be minimal changes to the LED and switching circuit. Changes will be made to
437 the position of the switching devices, placing them slightly closer to each other to reduce
438 transmission line length. The LED will likely remain as the LC LED UT-67UV365P 365nm
439 0805 LED, but further LED tests will be performed. This takes a short amount of time, and
440 may lead to discovering better LEDs in the future which would be easy to swap in due to
441 standardised footprints.

442 **6.10.2 LVDS-to-TTL converter**

443 No changes are expected to this circuit.

444 **6.10.3 Power supplies**

445 Reverse voltage bias will be removed as no difference between normal and reverse bias was
446 observed photon output. The overcurrent protection and power enable circuit will be re-
447 worked.

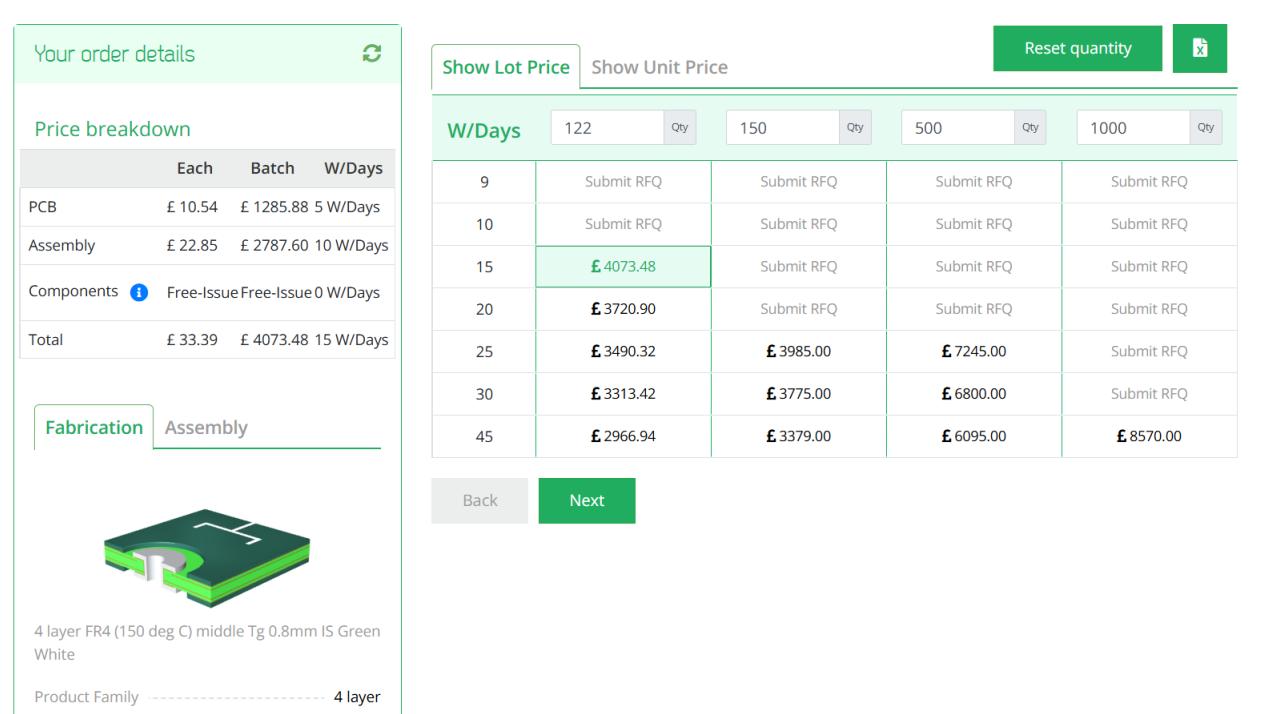


Figure 28: PCBTrain PCB production and assembly costs

448 6.10.4 Connector

449 No changes are expected to this.

450 6.10.5 Fibre coupler

451 A brand new fibre coupler will be designed due to the recent requirement changes regarding
452 the different fibre lengths.

453 7 Server Rack and Cooling

454 To house the electronics for the LI systems, two 42U server racks with 800 mm depth will
455 be used. The front of the server rack will be used for electrical connections and displays,
456 and the reverse/internal will be used only for fibre routing. The server racks will include
457 Uninterruptible Power Supplies (UPS) for safe power delivery and for power processing, to
458 avoid issues with potential instabilities in the main power supply. Each rack will include an
459 air conditioning unit to have a controlled temperature and remove humidity from the air,
460 as the relative humidity in the air is expected to be above 70%. Although specific tests on
461 running the LED electronics in humid conditions have not been carried out, it is known that
462 the optical switches for the laser calibration system requires lower humidity levels. In order
463 to simplify things and remove the potential of humidity issues with the LED electronics,
464 both server racks will be air conditioned. These systems are widely available and will be
465 chosen closer to installation.

466 **8 LED Monitoring**

467 To monitor the light output from the LEDs before attenuation by fibres and convolution
468 with water parameters, PMTs will be placed near to the LED sources. This is a similar
469 design to what is currently used in the Super-K UKLI system. Each LED connector will
470 feature a second fibre to take light to a series of PMTs, which are expected to be Hamamatsu
471 H10721-210. Due to the 8 mm diameter of the PMT window, up to 16 fibres can be attached,
472 meaning one PMT can monitor up to 16 LED boards at once. Each PMT will be powered
473 by a unique low cost power supply developed for the SK UKLI system. These will be housed
474 in a small 2–3 U server rack. The signals from the PMTs will then go to the dedicated HK
475 electronics channels that are set up for monitoring.

476 **9 Control System for LEDs**

477 The LEDs are driven by a differential LVDS signal originating from the FPGA. The FPGA
478 in use is the Genesys 2 [17] development board, which operates a pulsing VHDL module
479 clocked at 300 MHz. Pulses are generated on the rising edge of this clock, and toggling the
480 output (i.e., asserting and then deasserting the trigger) requires a minimum of two clock
481 cycles. Consequently, the shortest achievable pulse duration in this configuration is 3.3 ns.

482 One of the main limitations of this setup is the coarse time resolution: pulse durations
483 are effectively constrained to integer multiples of 3.3 ns. To achieve a broader and more
484 finely resolved spectrum of optical injection into the detector, improved temporal precision
485 is necessary. This is accomplished using the Xilinx IODELAY primitive, originally designed for
486 high-speed interface timing alignment. The IODELAY module permits fine-tuning of signal
487 timing to account for PCB trace mismatches, and in this application, it is repurposed to
488 introduce controlled delays between pulses.

489 To generate shorter pulses, two identical signals are created, one of which is delayed
490 using IODELAY. These signals are then combined using a logical AND operation, producing
491 a narrower pulse. Since the IODELAY module requires one clock cycle to process the input,
492 both signals—regardless of whether they are delayed—must pass through an IODELAY stage
493 to ensure temporal synchronisation.

494 Conversely, to produce longer pulses, the same methodology is applied, but the signals are
495 combined using a logical OR gate instead. This approach extends the pulse width beyond the
496 base clock resolution, enabling pulse durations ranging from approximately 1.5 ns to 4.5 ns
497 in 49 discrete steps. The lower bound is determined by the threshold of the LVDS-to-TTL
498 converter, which does not respond to pulses shorter than approximately 1.5 ns .

499 For channels using the longest optical fibres, this extended range is sufficient, given
500 the intrinsic dispersion in the fibre optics of around 5 ns. However, shorter fibres require
501 additional pulse shaping. To this end, an additional mechanism is implemented using a for
502 loop structure within the FPGA logic. This allows the pulse to persist for multiple clock
503 cycles, effectively producing longer pulses by repetition. However, due to FPGA architecture
504 constraints, each iteration of the loop consumes a clock cycle, necessitating careful timing
505 control. For instance, to produce a 6.6 ns pulse, the loop must be configured for two cycles,
506 accounting for the loop overhead.

507 Further refinement is under investigation through the daisy-chaining of multiple IODELAY
508 modules. This would enable sub-nanosecond granularity by introducing additional interme-
509 diate delay steps. While promising, this technique requires further validation and testing.

510 The pulse control data structure is currently under development. There are two types
511 of pulse description considered. In the first option, the software interface would require two
512 parameters per channel: a *coarse* step and a *fine* step, reflecting the approach used in the SK

513 system. The other option would be just a single variable and then simple logic turning that
514 variable into the *coarse* and *fine* step that the internal logic requires. Two hardware modules
515 are planned: one for generating the single shortest possible pulse (to minimise latency), and
516 another for multi-cycle pulses using programmable duration. A selection logic will assess the
517 input and route it to the appropriate module based on the desired pulse characteristics.

518 Each LED channel will be controlled independently, allowing for unique pulse configura-
519 tions across channels. The global trigger will be derived from the system clock, and each
520 channel will pulse in a predefined sequence while triggered from the global trigger. This
521 architecture also supports simultaneous pulsing of multiple channels. Should asynchronous
522 behaviour be required, additional per-channel delay logic can be implemented. Given the
523 five distinct fibre lengths used in the system, each channel group will also include a config-
524 urable delay offset to compensate for propagation time differences. These group delays will
525 be calibrated and fixed, with the option of fine-tuning individual channels post-deployment
526 if necessary.

527 The FPGA programming remains in active development. Inter-crate communication
528 protocols and synchronisation are currently under integration and testing.

529 10 Crate Electronics

530 10.1 Overview

531 The system specification calls for control of up to 122 LED channels, significantly exceeding
532 the channel counts used in current systems such as Super-Kamiokande or LUX-ZEPLIN,
533 which the previous generation of pulser boards are used for. To manage this complexity, the
534 design prioritises ease of use, maintainability, and straightforward deployment, particularly
535 given that the server racks will accommodate hundreds of optical fibres.

536 To achieve this, a system concept originally developed by ATLAS collaborators (specifi-
537 cally by Ashley Greenal) has been adapted. The original design utilises a Genesys 2 FPGA
538 integrated into a half-width Verotec KM6-2 [18] Eurocard-compatible crate for testing pur-
539 poses. This concept has been extended to a full 19-inch rack width, enabling the integration
540 of up to 36 pulser boards within a single crate.

541 Each FPGA is capable of interfacing with up to 38 pulser boards, thereby maximising
542 the utilisation of available LVDS differential pairs, with an additional pair reserved for the
543 laser trigger signal. This configuration ensures full use of the Genesys 2's I/O capacity while
544 maintaining flexibility for future expansion.

545 The system architecture consists of three primary components: the Blade (Section 10.2),
546 Backplane (Section 10.3) and Eurocard (Section 10.4). This modular approach ensures
547 scalability and facilitates debugging, replacement, and upgrades. It also provides a robust
548 foundation for managing high channel counts while maintaining signal integrity and synchro-
549 nisation across the system.

550 10.2 Blade

551 The Blade is a simple, eight layer board, that has a SEAM-40-06.5-L-10-2-A-K-TR [19]
552 connector which is a direct fit for the Genesys 2's FMC connector. It features a PCIE 16X
553 connector at the edge for connectivity to the Backplane. The PCIE was selected by Ashley
554 Greenal as it is a well documented standard connector and there are a large amount of
555 connectors available that can be bought easily. While PCIE connectors are being used, the
556 PCIE standards for communication are not. This is a very dense PCB with all the differential
557 tracks on it, so buried vias and multiple layers will be used. See Figure 29 for a work in
558 progress version.

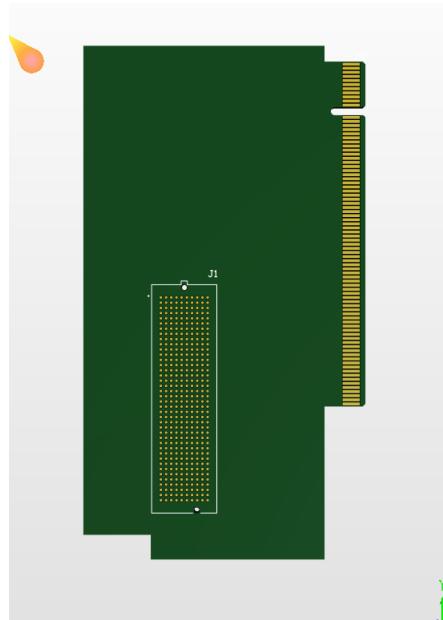


Figure 29: Blade Work in Progress

559 10.3 Backplane

560 The Backplane serves two primary functions: the distribution of differential signals from the
 561 Blade to the Eurocards, and the reception and distribution of power throughout the crate
 562 system. It accepts external power inputs of 12 V and ± 5 V, and includes a basic regulation
 563 circuit to stabilise these supply voltages for downstream use.

564 Given the mechanical constraints and routing complexity, the Backplane is implemented
 565 as a four-layer PCB with impedance-controlled traces to ensure signal integrity across all
 566 differential pairs. It features a single PCIe x16 connector to interface with the Blade, and
 567 three PCIe x8 connectors to interface with the Eurocards.

568 The Eurocards are positioned at slots 2, 8, and 64 within the crate. This arrangement
 569 creates two symmetrical chambers with 48 units spacing between cards, ensuring adequate
 570 space to accommodate the minimum long-term bend radius of the FP400URT optical fibres.
 571 This layout balances mechanical reliability with signal routing efficiency and supports long-
 572 term maintainability of the system. See Figure 30 for a work in progress version.

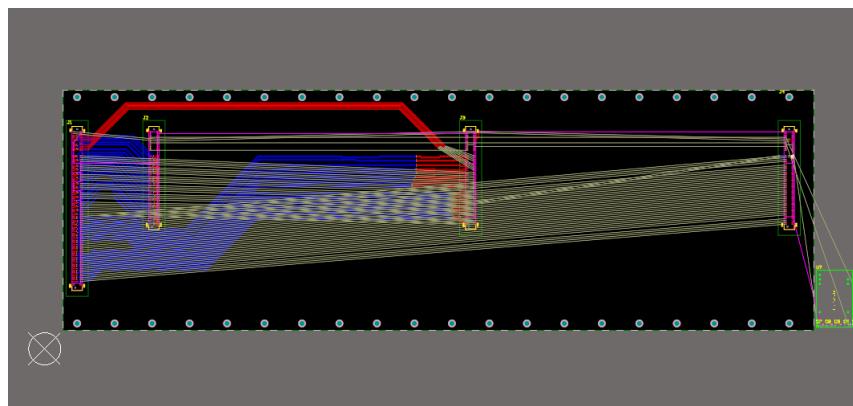


Figure 30: Backplane Work in Progress

573 **10.4 Eurocard**

574 The Eurocard format defines the physical and electrical standard for the crate system, hence
575 the naming convention. Each Eurocard is equipped with a PCIe x8 connector for interfacing
576 with the Backplane, and is designed to host up to 18 pulser boards—nine mounted on each
577 face. Pulser boards connect via FS-1332120 Male[20] connectors, and each socket includes
578 two mounting holes for mechanical standoffs.

579 The board layout on each side consists of two staggered rows: five sockets in the back
580 row and four in the front. The two faces are laterally offset by approximately 10 mm to
581 prevent interference or fibre clashes when the system is fully populated and enclosed within
582 the crate chamber. This offset ensures smooth fibre routing and accommodates the bend
583 radius requirements of FP400URT fibres.

584 Power distribution within each Eurocard is handled by a THD 12-1212 [21]12 V DC-DC
585 regulator. This regulator provides local power isolation for the pulser boards and includes
586 a control pin connected to a PCA9698 [22] 40-pin GPIO expander. This allows for system-
587 level control, enabling or disabling all pulser boards on a card—an essential feature during
588 power-up, especially when the FPGA may inadvertently drive all differential outputs high
589 during reprogramming.

590 The GPIO expander is responsible for enabling the local 12 V regulator and for selectively
591 powering individual pulser boards. This facilitates fault isolation and power savings in
592 channels that are inactive or disconnected. Additional GPIO pins are assigned to monitor
593 output voltage levels via the overcurrent sensing circuitry.

594 To provide per-channel LED power control, an AD5673 [23] DAC is included. It out-
595 puts analogue control voltages to the onboard adjustable regulators on each pulser board,
596 allowing for independent LED drive voltage per channel. Both the GPIO and DAC devices
597 communicate with the system over the I²C protocol.

598 For laser synchronisation, the Eurocard includes a differential-to-NIM conversion stage.
599 This consists of an LVDS-to-TTL converter identical to that used on the pulser boards,
600 followed by a TTL-to-NIM converter. This ensures compatibility with legacy NIM-based
601 timing systems used in external laser triggering. See Figure 31 for a work in progress version.

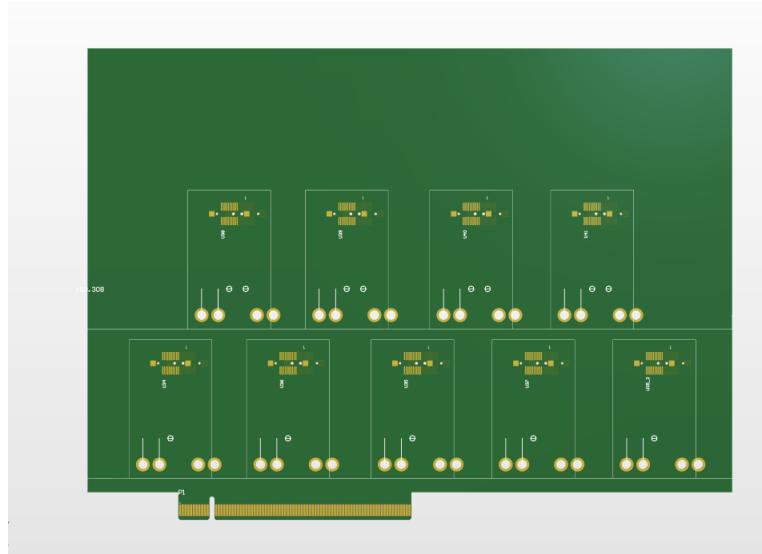


Figure 31: Eurocard Work in Progress

602 **11 Conclusions**

603 Write this

604 **References**

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